



FIG. 2

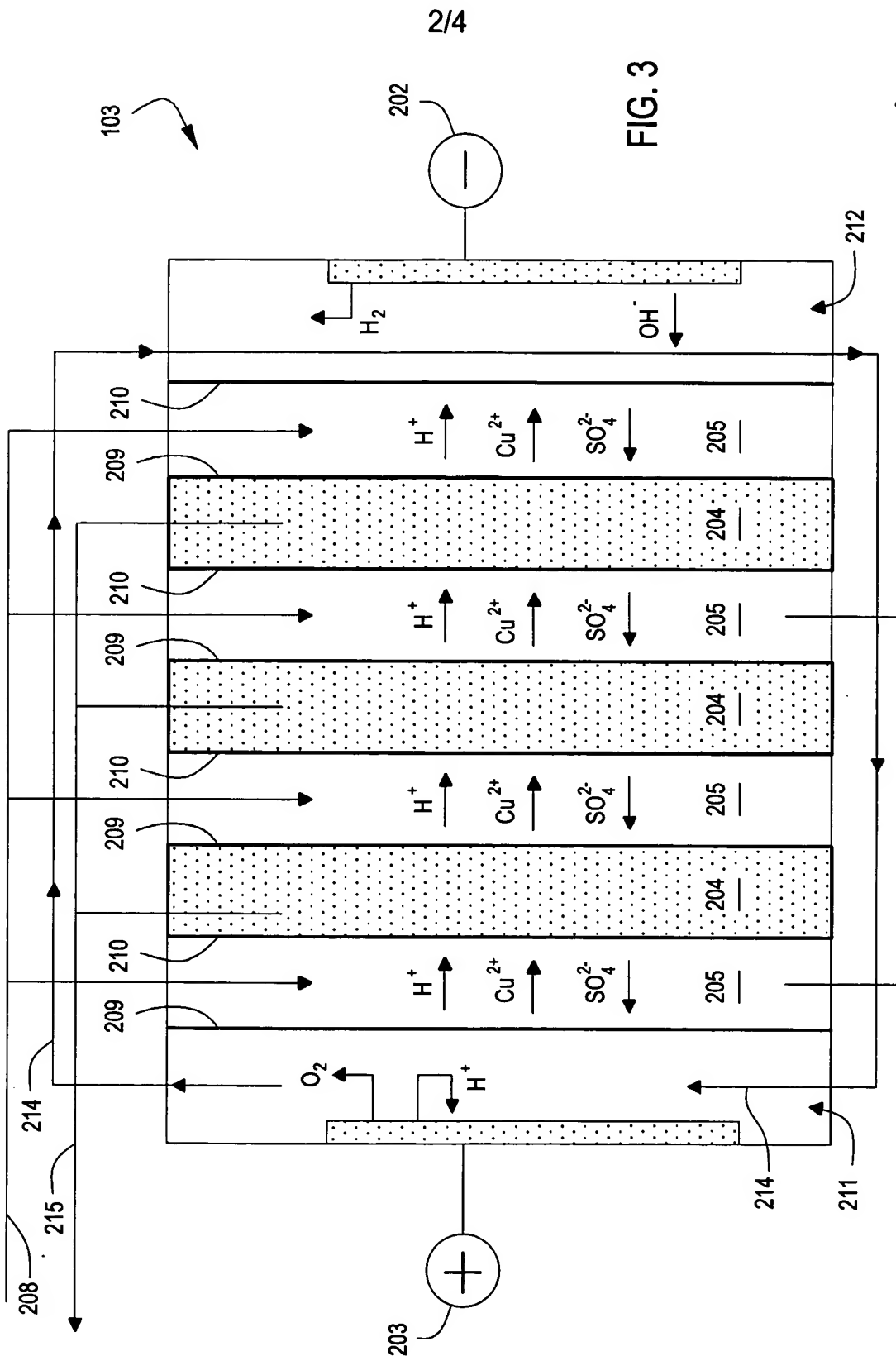


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Apparatus and Method for Removing Contaminants from Semiconductor
Copper Electroplating Baths
Kovarsky, et al.

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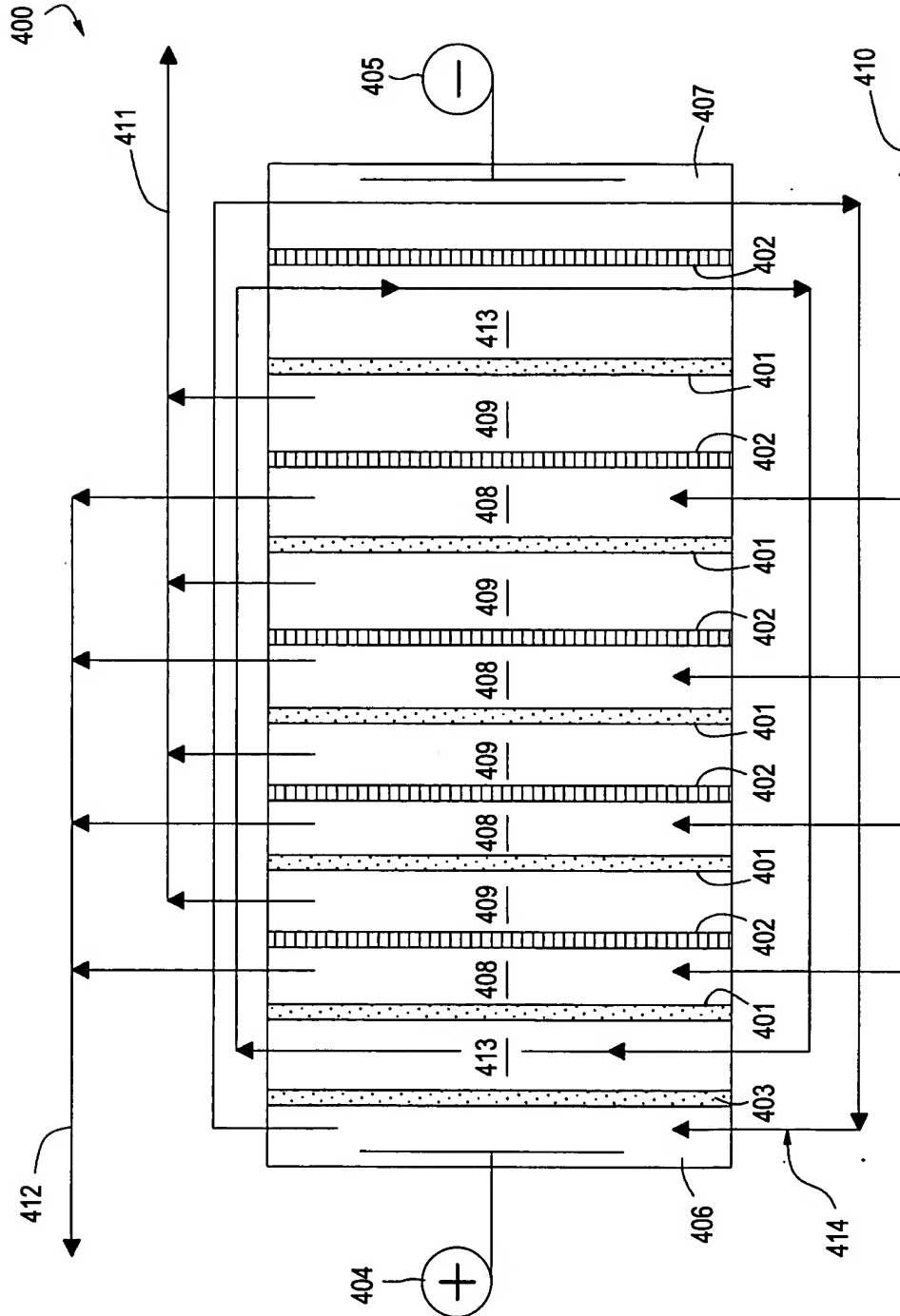


FIG. 4

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FIG. 5

